

Title (en)  
RIC SDK

Title (de)  
RIC SDK

Title (fr)  
SDK RIC

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Application  
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- US 202163157351 P 20210305
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  - US 202163176859 P 20210419
  - US 202163180627 P 20210427
  - US 202117376801 A 20210715
  - US 202117376835 A 20210715
  - US 202117376758 A 20210715
  - US 202117376817 A 20210715
  - US 202163225519 P 20210725
  - US 202117384777 A 20210725
  - US 2022013427 W 20220121

Abstract (en)  
[origin: WO2022186912A1] To provide a low latency near RT RIC, some embodiments separate the RIC's functions into several different components that operate on different machines (e.g., execute on VMs or Pods) operating on the same host computer or different host computers. Some embodiments also provide high speed interfaces between these machines. Some or all of these interfaces operate in non-blocking, lockless manner in order to ensure that critical near RT RIC operations (e.g., datapath processes) are not delayed due to multiple requests causing one or more components to stall. In addition, each of these RIC components also has an internal architecture that is designed to operate in a non-blocking manner so that no one process of a component can block the operation of another process of the component. All of these low latency features allow the near RT RIC to serve as a high speed IO between the E2 nodes and the xApps.

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BA ME

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KH MA MD TN

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